Development checklist for STM32Cube Expansion Packages

Introduction

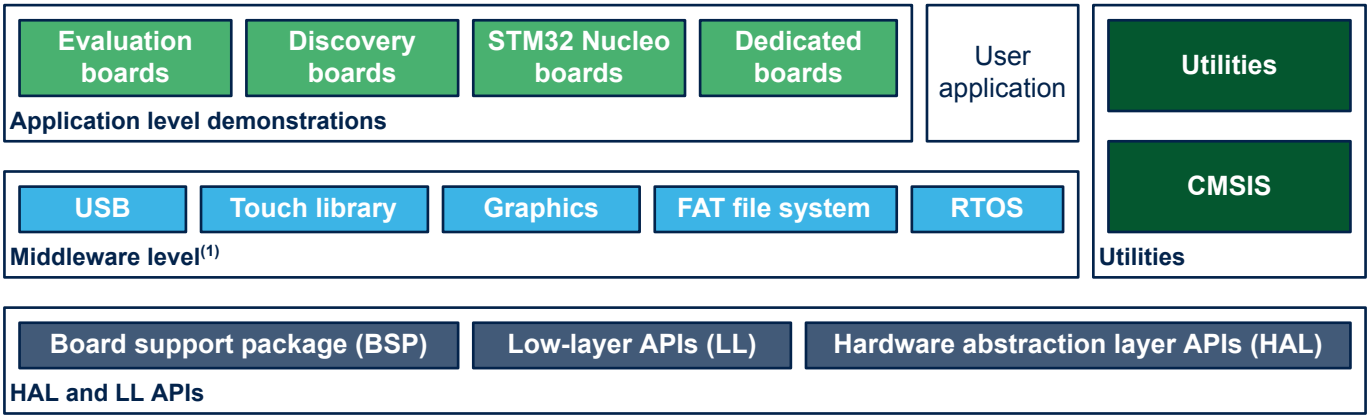
STM32Cube is an STMicroelectronics original initiative to improve designer productivity significantly by reducing development effort, time, and cost. STM32Cube covers the whole STM32 portfolio.

STM32Cube includes:

- A set of user-friendly software development tools to cover project development from the conception to the realization, among which STM32CubeMX, a graphical software configuration tool, STM32CubeIDE, an all-in-one development tool, STM32CubeProgrammer (STM32CubeProg), a programming tool, and a set of powerful monitoring tools such as STM32CubeMonitor.
- STM32Cube MCU and MPU Packages, comprehensive embedded-software platforms specific to each microcontroller and microprocessor series (such as STM32CubeL4 for the STM32L4 Series), which include STM32Cube hardware abstraction layer (HAL), STM32Cube low-layer APIs, a consistent set of middleware components, and all embedded software utilities.
- STM32Cube Expansion Packages, which contain embedded software components that complement the functionalities of the STM32Cube MCU and MPU Packages with middleware extensions and applicative layers, and examples.

For a more complete description of STM32Cube, refer to What is STM32Cube?

Figure 1. STM32Cube MCU and MPU Packages components



(1) The set of middleware components depends on the product Series.

The proper development of the STM32Cube Expansion Package depends on criteria related to quality, packaging, middleware support, documentation, and others.

This document is a checklist describing all criteria together with their level of importance. These must be met to ensure the compliance of the STM32Cube Expansion Package with each STM32Cube MCU or MPU Package and, further, overall coherence with the global STM32Cube offering. Report the status for all criteria in the tables from Table 2 to Table 9.

1 General information

The STM32Cube MCU and MPU Packages and STM32Cube Expansion Packages run on STM32 32-bit microcontrollers based on the Arm® Cortex®-M processor.

Note: Arm is a registered trademark of Arm Limited (or its subsidiaries) in the US and/or elsewhere.

1.1 References and acronyms

The following documents available on *www.st.com* are references for the development of STM32Cube Expansion Packages:

- *Development guidelines for STM32Cube Expansion Packages* (UM2285)
- *Development guidelines for STM32Cube firmware Packs* (UM2388)
- *STM32Cube BSP drivers development guidelines* (UM2298)
- *How to create a software pack enhanced for STM32CubeMX using STM32 Pack Creator tool* (UM2739)

Table 1 presents the definitions of the relevant acronyms for a better understanding of this document.

Table 1. List of acronyms

Term	Definition
API	Application programming interface
BSP	Board support package
CMSIS	Cortex Microcontroller Software Interface Standard
HAL	Hardware abstraction layer
HW	Hardware
LL	Low-layer
SW	Software

2 What is STM32Cube?

STM32Cube is an STMicroelectronics original initiative to improve designer productivity significantly by reducing development effort, time, and cost. STM32Cube covers the whole STM32 portfolio.

STM32Cube includes:

- A set of user-friendly software development tools to cover project development from conception to realization, among which are:
  - STM32CubeMX, a graphical software configuration tool that allows the automatic generation of C initialization code using graphical wizards
  - STM32CubeIDE, an all-in-one development tool with peripheral configuration, code generation, code compilation, and debug features
  - STM32CubeProgrammer (STM32CubeProg), a programming tool available in graphical and command-line versions
  - STM32CubeMonitor (STM32CubeMonitor, STM32CubeMonPwr, STM32CubeMonRF, STM32CubeMonUCPD) powerful monitoring tools to fine-tune the behavior and performance of STM32 applications in real time
- STM32Cube MCU and MPU Packages, comprehensive embedded-software platforms specific to each microcontroller and microprocessor series (such as STM32CubeL4 for the STM32L4 Series), which include:
  - STM32Cube hardware abstraction layer (HAL), ensuring maximized portability across the STM32 portfolio
  - STM32Cube low-layer APIs, ensuring the best performance and footprints with a high degree of user control over hardware
  - A consistent set of middleware components such as RTOS, USB Host and Device, FAT file system, touch library, and graphics
  - All embedded software utilities with full sets of peripheral and applicative examples
- STM32Cube Expansion Packages, which contain embedded software components that complement the functionalities of the STM32Cube MCU and MPU Packages with:
  - Middleware extensions and applicative layers
  - Examples running on some specific STMicroelectronics development boards

3 STM32Cube Expansion quality criteria

Table 2. Quality criteria

ID	Item description	Importance	Comments[1]
C.Q1	BSP drivers, middleware, and projects developed within the STM32Cube Expansion Package (add-on to the STM32Cube MCU Package) must meet the minimum requirements below: • Ensure compilation with all supported toolchains (IAR Systems EWARM, Keil® MDK-ARM, and STMicroelectronics STM32CubeIDE) on Windows® and Linux® platforms, without errors neither warnings. *Note: warnings are accepted only in SW components not owned by the developer of the Expansion Package.* • Perform functional tests with evidence reports with no known bugs left. *Note: minor bugs are accepted provided they are documented in the component release notes.*	Mandatory	-
C.Q2	Middleware, BSP and component drivers developed within the STM32Cube Expansion Package (add-ons with respect to the STM32Cube MCU Package) must be compliant with the MISRA C® coding standard and checked with static code analysis, with evidence reports. *Note: any deviation must be precisely justified.*	Recommended	-
C.Q3	All source code provided must be documented through comments explaining the functional behavior.	Mandatory	-

1. *PASSED / FAILED / NOT APPLICABLE. If FAILED, provide additional comments.*

4 STM32Cube Expansion packaging criteria

Table 3. Packaging criteria

ID	Item description	Importance	Comments[1]
C.P1	The STM32Cube Expansion Package must have the same repository hierarchy as the STM32Cube MCU Package (refer to section *4.3 Packaging model* in UM2388).	Mandatory	-
C.P2	Native software components provided within the STM32Cube MCU Package must not be modified (it is, for instance, forbidden to delete a release note or an unused file, or to modify any source code).	Mandatory	-
C.P3	A global release note must be provided for the STM32Cube Expansion Package. It must contain the following sections: • Main changes Lists the main changes with respect to the previous release • Content Lists all the software components developed for the STM32Cube Expansion Package and those reused from the STM32Cube MCU Package • Development toolchains and compilers Lists the supported toolchains and their versions • Supported devices and hardware boards Lists the supported STM32 devices and the boards (together with their versions) used to run the examples • Known limitations Lists the main known limitations if any	Mandatory	-
C.P4	A release note must be provided for each software component. It must contain the date and version number of the software component files. *Note: date and version are not required to be within the software components files.*	Mandatory	-
C.P5	Application specific files and added software components must have a license information in the source file header and release note.	Recommended	-
C.P6	New BSP drivers must be added under `\Drivers\BSP\<Board-Name>`. If a new hardware component driver is needed, it must be added under `\Drivers\BSP\Components`. *Note: <Board-Name> must comply with the rules described in section "6.4.4 Description of BSP Class drivers" of UM2388.*	Mandatory	-
C.P7	Third-party new middleware component (not part of the STM32Cube Expansion Package) must be located under `\Middlewares\Third_Party`.	Mandatory	-
C.P8	Example projects must be added under `\Projects\<Board-Name>` and classified as follows: • Examples: using only HAL and BSP • Applications: using middleware • Demonstration: using HAL, BSP and middleware *Note: <Board-Name> must be the board part number as referenced in the STM32 Nucleo boards page of the www.st.com website, and also described in section "6.4.4 Description of BSP Class drivers" of UM2388.*	Mandatory	-

ID	Item description	Importance	Comments[1]
C.P9	Example projects must respect either the basic structure or advanced structure organization as described in UM2388. *Note: examples generated by STM32CubeMX are by default in the advanced structure.*	Mandatory	-
C.P10	Example projects must be generated using STM32CubeMX. Peripheral initialization and middleware configuration must be generated by STM32CubeMX.	Mandatory	-
C.P11	The files `*.ioc`, `.mxproject`, and `.extSettings` (optional, if available) must be provided at the same location as the `readme.txt` in the example folder. *Note: these files are generated by STM32CubeMX.*	Mandatory	-
C.P12	The `*.ioc` file must comply with the following convention: `Application#N.ioc`.	Mandatory	-
C.P13	All media files (such as. images, audio, videos, and others), when used, must be located under `\Utilities\Media` and a `readme` file explaining the copyright/license of each used media file must be added.	Mandatory	-
C.P14	Each software file (that is any application running on a PC compatible platform), when used, must be located under `\Utilities\PC_Software` and a `readme` file explaining the tool license and how to use it must be added.	Mandatory	-
C.P15	For each example; a preconfigured project must be provided for IAR Systems EWARM, Keil® MDK-ARM, and STMicroelectronics STM32CubeIDE toolchains.	Mandatory	-
C.P16	Non-user files must not be present in the STM32Cube Expansion Package (such as. `tmp` files, object files generated by IDE, CMP files (`.git`, `.svn`, or others)).	Mandatory	-

1. *PASSED / FAILED / NOT APPLICABLE. If FAILED, provide additional comments.*

5 STM32Cube Expansion BSP criterion

Table 4. BSP criterion

ID	Item description	Importance	Comments[1]
C.B1	Any new BSP driver (not part of the STM32Cube MCU Package) must comply with the STM32Cube BSP drivers development guidelines (refer to UM2298).	Mandatory	-

1. *PASSED / FAILED / NOT APPLICABLE. If FAILED, provide additional comments.*

6 STM32Cube Expansion middleware criterion

Table 5. Middleware criterion

ID	Item description	Importance	Comments[1]
C.M1	Middleware must be hardware and platform independent and the link with the low layers must be provided by means of an interface file.	Mandatory	-

1. *PASSED / FAILED / NOT APPLICABLE. If FAILED, provide additional comments.*

7 STM32Cube Expansion documentation criteria

Table 6. Documentation criteria

ID	Item description	Importance	Comments[1]
C.D1	Each newly added software component (such as BSP or middleware) must have its API documented in a user manual. This user manual can be in `.pdf` format or in a format for online documentation such as `.html` or `.chm`.	Mandatory	-
C.D2	Each example project must come with detailed explanation, functional description, and hardware setup.	Mandatory	-

1. *PASSED / FAILED / NOT APPLICABLE. If FAILED, provide additional comments.*

8 STM32Cube Expansion terminology criteria

Table 7. Terminology criteria

ID	Item description	Importance	Comments[1]
C.T1	When referring to products (both HW and SW), always use the full and correct part number (for instance, use NUCLEO-F401RE, all uppercase, for the *STM32 Nucleo-64 development board with STM32F401RE MCU*, instead of *"Nucleo F4"* or similar inappropriate terms). The *"STM32 Nucleo"* brand must be used exactly as in the STM32 Nucleo boards page of the *www.st.com* website, without any modifications (such as spaces, upper/lower case, and others).	Mandatory	-
C.T2	When referring to boards that can be plugged onto STM32 Nucleo boards, always use the term *"STM32 expansion board"*. No other name is allowed (such as shield or others).	Mandatory	-

1. *PASSED / FAILED / NOT APPLICABLE. If FAILED, provide additional comments.*

9 STM32Cube Expansion Package commercial offering criteria

Table 8. Commercial offering criteria

ID	Item description	Importance	Comments[1]
C.C1	For a commercial STM32Cube Expansion Package, a free version of this software Expansion Package must be provided for evaluation. Each ST partner can choose its own strategy for the free evaluation version, such as: • Middleware delivered as a binary, and time limited (time bombed, reset after a timeout or others) • Middleware delivered as a binary, with limited features	Mandatory	-
C.C2	An example must be provided, running on an STM32 board (Discovery board, Nucleo board, or Evaluation board) or a board widely available at STM32 distributors.	Mandatory	-

1. *PASSED / FAILED / NOT APPLICABLE. If FAILED, provide additional comments.*

10 STM32Cube Expansion Package enhanced for ST toolset criteria

Table 9. ST toolset criteria

ID	Item description	Importance	Comments[1]
C.X1	The STM32Cube Expansion Package enhanced for the ST toolset must comply with the rules described in the user manual Development guidelines for STM32Cube firmware Packs (UM2388). *Note: all deviations must be justified.* *Note: the STM32PackCreator tool in STM32CubeMX displays a tooltip for this rule.*	Mandatory	-
C.X2	The STM32Cube Expansion Package name must be `<vendor>.<name>-<Feature>.<version>` where: • `<name>` is: – `X-CUBE` for STMicroelectronics Expansion Packages – `I-CUBE` for partner and third-party Expansion Packages • `<Feature>` is the application domain *Note: the STM32PackCreator tool in STM32CubeMX displays a tooltip for this rule.*	Mandatory	-
C.X3	The STM32Cube Expansion Package `PDSC` file must be checked with Arm® `PackChk.exe`. *Note: information about the `PackChk.exe` used must be provided.*	Mandatory	-
C.X4	The STM32Cube Expansion Package release note must contain the URL of the software license agreement (SLA).	Mandatory	-
C.X5	The `<keyword>` tags of the STM32Cube Expansion Package `PDSC` file must be used to provide additional relevant information such as: • minimum memory requirements • supported STM32 Series (such as STM32F4, STM32F7 or others) • supported boards • supported core *Note: the STM32PackCreator tool in STM32CubeMX displays a tooltip for this rule.*	Mandatory	-
C.X6	In the STM32Cube Expansion Package `PDSC` file, a new `<release>` field must be added each time a new pack is released, containing a significative list of changes described using clear and short messages. The mindset must be similar to the one applied to GIT Kernel comments. *Note: the STM32PackCreator tool in STM32CubeMX displays a tooltip for this rule.*	Mandatory	-
C.X7	In the STM32Cube Expansion Package `PDSC` file, the `<apis>` section must contain all the APIs relative to the elements in the `.pack` file, pointing to: • a header file using the `<header>` attribute, where the APIs are presented in terms of function prototypes • a `CHM` file using the `<doc>` attribute, describing the APIs and parameters through Doxygen comments • *Note: the STM32PackCreator tool in STM32CubeMX displays a tooltip for this rule.*	Recommended	-

ID	Item description	Importance	Comments[1]
C.X8	A `doc/` folder, containing the `CHM` file describing APIs and parameters of middleware elements, must be located at the same level as the middleware `Release_Notes`.	Recommended	-
C.X9	All non-user comments must be removed from the `PDSC` file.	Mandatory	-
C.X10	Any change in the APIs for a component must be identifiable by means of a new `cVersion` value in the `PDSC`, according to the following rules: • `<x.y.z>` where: – `x` is a major change: new features, API compatibility break with previous version, or both – `y` is a minor change: implementation enhancement, bug fix, or both – `z` is a patch • `<x.y.z-aaa+bbbbb>` syntax must be used for internal or intermediated beta deliveries, where `aaa` and `bbbbb` are optional *Note: the STM32PackCreator tool in STM32CubeMX displays a tooltip for this rule.*	Mandatory	-
C.X11	All non-user comments must be removed from the `IPconfig` and `IPmodes` files, when available.	Mandatory	-
C.X12	To improve packs traceability, `Cversion` must be aligned with the `git-repo` tag If a `<component>` contains two or more repositories (like MEMS where `BSP` and `Component Drivers` are combined), the `Cversion` is determined by the highest level in the SW stack (BSP).	Recommended	-
C.X13	To ensure compatibility with underlying pack new versions, conditions must include version numbers in the STM32Cube Expansion Package `PDSC` file, such as: `<require Cbundle="BlueNRG-MS" Cclass="Wireless" Cgroup="Controller" Cversion="4.4.0">`	Mandatory	-
C.X14	The following line must be removed from the `.ioc` included in the example folder: `ProjectManager.FirmwarePackage=`	Mandatory	-

1. *PASSED / FAILED / NOT APPLICABLE. If FAILED, provide additional comments.*

Revision history

Table 10. **Document revision history**

Date	Revision	Changes
14-Nov-2017	1	Initial release.
6-Sep-2019	2	Updated *Importance* of *C.Q2* in *Table 2: Quality criteria* and *C.M1* in *Table 4: Middleware criteria*. Updated the description of STM32Cube on the cover page and in *Chapter 3*.
9-Sep-2020	3	Document entirely revisited. Updated: • *STM32Cube Expansion quality criteria* • *STM32Cube Expansion packaging criteria* • *STM32Cube Expansion middleware criterion* • *STM32Cube Expansion documentation criteria* • *STM32Cube Expansion Package commercial offering criteria* • *References and acronyms* • *What is STM32Cube?* Added: • *STM32Cube Expansion BSP criterion* • *STM32Cube Expansion terminology criteria* • *STM32Cube Expansion Package enhanced for ST toolset criteria*
18-Feb-2021	4	Updated criterion C.P16 in *STM32Cube Expansion packaging criteria*. Removed criterion C.P17. Updated criterion C.X2 in *STM32Cube Expansion Package enhanced for ST toolset criteria*.
23-Jun-2022	5	Updated criterion C.P11 in STM32Cube Expansion packaging criteria.

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